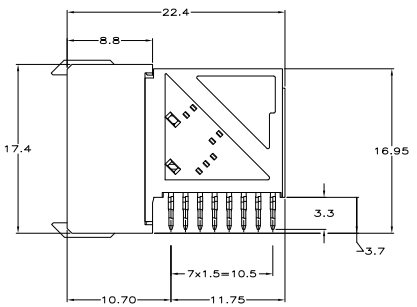
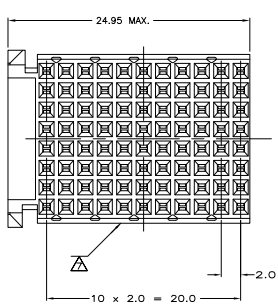
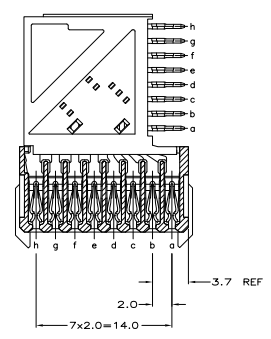
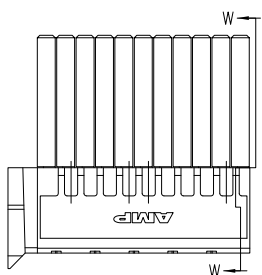
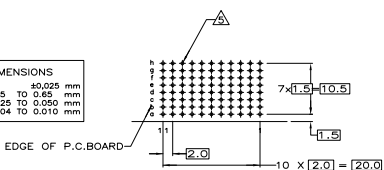


REV	DATE	DESCRIPTION	BY	CHKD
C	22FEB11	REV PER IEC 608-11-003871	RC	CW
D	13DEC11	EDS-11-004691	SY	MOV



PCB HOLE DIMENSIONS	
DRILLED HOLE	0.7 ±0.025 mm
FIN. HOLE	2.55 TO 0.05 mm
Cu-thks	0.025 TO 0.050 mm
SnPb-thks	0.004 TO 0.010 mm



RECOMMENDED PCB HOLE LAYOUT
 COMPONENT SIDE
 SCALE 2.5:1

- ▲ MATERIAL:
 CONTACT: PHOSPHOR BRONZE.
 HOUSING: GLASS-FILLED POLYESTER.
- ▲ GENERAL PLATING SPECIFICATION: UNDERPLATING
 (ENTIRE CONTACT): 1.27µm MIN NICKEL AND ACTION
 FIN: 0.5µm MIN TIN.
 FOR PLATING OF MATING SURFACES SEE APPLICABLE
 SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- ▲ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101
 PERFORMANCE LEVEL 2.
- ▲ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,
 CENTRAL OFFICE APPLICATIONS.
- ▲ PLATED THROUGH HOLES AT 2x1.5mm GRID, 88 TOTAL HOLES.
- ▲ CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT.
 TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 1, NOVEMBER 1995.
- ▲ CONNECTOR PRINTED WITH PART NUMBER AND DATE CODE THIS SIDE.
 ADDITIONAL CHARACTERS OR MARKINGS, AS WELL AS THE LOCATION OF THE MARKINGS,
 MAY BE ADDED FOR TRACEABILITY BASED UPON MANUFACTURERS DISCRETION.
- ▲ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- ▲ 0.76µm MIN GOLD PLATING ON MATING SURFACES

▲	3-646446-0
▲	-646446-9-
▲	646446-1
▲	FINISH
▲	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNER	DATE	REVISED	DATE
DR	11/05/08	DR	11/05/08
CHECKED	DATE	REVISED	DATE
DR	11/05/08	DR	11/05/08

Customer Drawing: R/A RECEPTACLE ASSY, 88 POSN, TTR
 8 ROW, TYPE F, Z-PACK 2mm HM

SIZE: A1 | DATE: 00779 | DRAWING NO: 5646446 | SHEET: 5:1 | OF: 1